



ZXTP03200BZ 200V PNP Low V_{CE}(sat) transistor in SOT89

Summary

BV_{CEO} > -200V $BV_{ECO} > -2V$ $I_{C(cont)} = 2A$ V_{CE(sat)} < -160mV @ -1A $R_{CE(sat)} = 130m\Omega$ $P_{D} = 2.4W$



Description

Packaged in the SOT89 outline this new 5th generation low saturation 200V PNP transistor offers extremely low on state losses making it ideal for use in DC-DC circuits and various driving and power management functions

Features

- 2 Amps continuous current •
- Up to 5 Amps peak current
- Very low saturation voltage
- Enhanced switching performance ٠

Applications

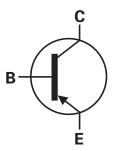
DC-DC Convertors

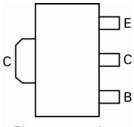
Ordering Information

Device	Reel size	Tape width	Quantity	
	(inches)	(mm)	per reel	
ZXTP03200BZTA	7	12	1000	

Device Marking

1N2





Pinout - top view

Absolute Maximum Ratings

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	-220	V
Collector-Emitter Voltage	V _{CEO}	-200	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current ^(a)	Ι _C	-2	А
Base Current	Ι _Β	-1	А
Peak Pulse Current	ICM	-5	А
Power Dissipation at T _A =25°C ^(a) Linear Derating Factor	PD	1.1 8.8	W mW/°C
Power Dissipation at T _A =25°C ^(b) Linear Derating Factor	PD	1.8 14.4	W mW/°C
Power Dissipation at T _A =25°C ^(C) Linear Derating Factor	PD	2.4 19.2	W mW/°C
Power Dissipation at T _A =25°C ^(d) Linear Derating Factor	PD	4.46 35.7	W mW/°C
Power Dissipation at T _c =25°C ^(e) Linear Derating Factor	PD	38.7 309.6	W mW/°C
Operating and Storage Temperature Range	T _j , T _{stg}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction to Ambient ^(a)	$R_{ heta JA}$	117	°C/W
Junction to Ambient ^(b)	$R_{ ext{ heta}JA}$	68	°C/W
Junction to Ambient ^(C)	$R_{\theta JA}$	51	°C/W
Junction to Ambient ^(d)	$R_{ ext{ heta}JA}$	28	°C/W
Junction to Lead ^(e)	R _{0JL}	3.23	°C/W

NOTES:

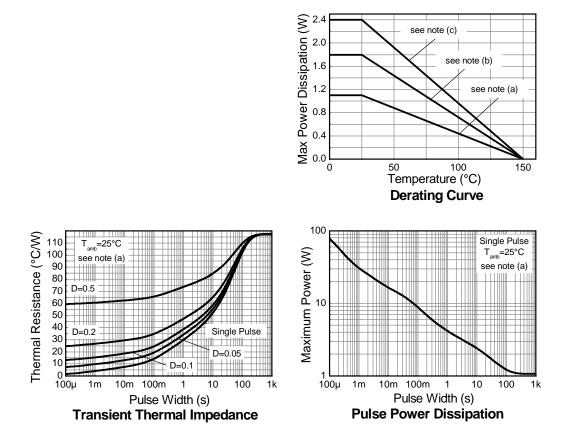
(a) For a device surface mounted on 15mm x 15mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

(b) Mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

(c) Mounted on 20mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions.
(d) As (c) above measured at t<5 seconds.

(e) Junction to Lead from Collector Tab. Typical

Thermal Characteristics



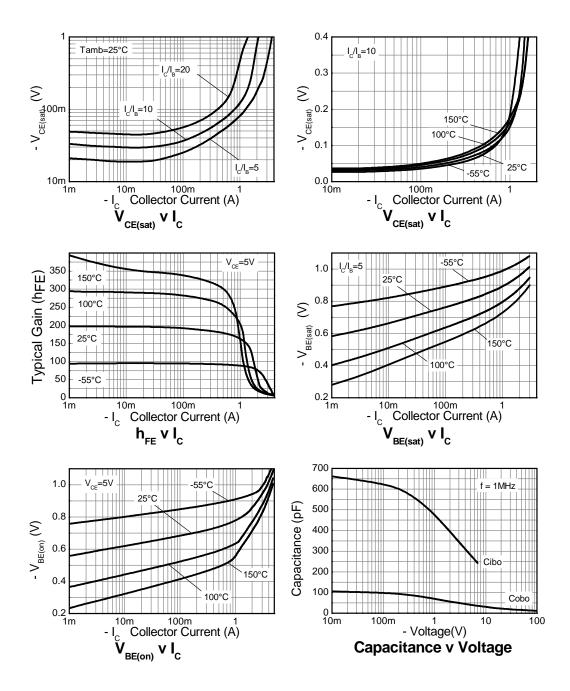
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Collector-Base Breakdown Voltage	BV _{CBO}	-220	-245		V	I _C = -100μA
Collector-Emitter Breakdown voltage	BV _{CER}	-220	-245		V	I _C = -1μΑ, R _{BE} ≤ 1kΩ
Collector-Emitter Breakdown Voltage	BV _{CEO}	-200	-225		V	I _c = -10mA ^(*)
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.4		V	I _E = -100μA
Collector-Base Cut-off	I _{CBO}		<1	-50	nA	V _{CB} = -200V
Current				-0.5	μA	V_{CB} = -200V, T_{amb} =100°C
Emitter Cut-off Current	I _{EBO}		<1	-10	nA	V _{EB} = -6V
Collector-Emitter Saturation	V _{CE(sat)}		-37	-50	mV	$I_{C} = -0.1A, I_{B} = -10mA^{(*)}$
Voltage			-120	-155	mV	$I_{C} = -0.5A, I_{B} = -25mA_{(*)}^{(*)}$
			-130	-160	mV	$I_{C} = -1A, I_{B} = -100 \text{mA}^{(^{)}}$
			-160	-260	mV	I _C = -2A, I _B = -400mA ^(*)
Base-Emitter Saturation Voltage	V _{BE(sat)}		-940	-1100	mV	I_{C} = -2A, I_{B} = -400mA ^(*)
Base-Emitter Turn-on Voltage	V _{BE(on)}		-840	-1000	mV	$I_{C} = -2A, V_{CE} = -5V^{(*)}$
Static Forward Current	h _{FE}	100	195			$I_{C} = -10 \text{mA}, V_{CE} = -5 V^{(*)}$
Transfer Ratio		100	170	300		I _C = -1A, V _{CE} = -5V ^(*)
		20	50			$I_{C} = -2A, V_{CE} = -5V^{(*)}$
			5			$I_{C} = -5A, V_{CE} = -5V^{(*)}$
Transition Frequency	f⊤		105		MHz	I _C = -100mA, V _{CE} = -10V f = 50MHz
Output Capacitance	C _{obo}		31		pF	$V_{CB} = -10V, f = 1MHz^{(*)}$
Delay Time	t _d		21		ns	
Rise Time	t _r		18		ns	I _C = -1A, V _{CC} = -50V,
Storage Time	t _s		680		ns	$I_{B1} = -I_{B2} = -100 \text{mA}$
Fall Time	t _f		75		ns	

Electrical Characteristics (at T_{amb} = 25°C unless otherwise stated)

NOTES:

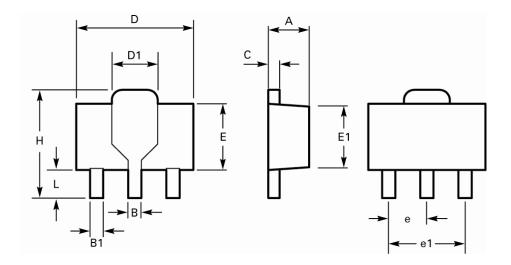
(*) Measured under pulsed conditions. Pulse width $\leq 300 \mu s;$ duty cycle $\leq 2\%.$

Typical Characteristics



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Package Information -SOT89



DIM	Millimete	ers	Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	1.40	1.60	0.550	0.630	е	1.40	1.50	0.055	0.059
b	0.38	0.48	0.015	0.019	E	3.75	4.25	0.150	0.167
b1	-	0.53	-	0.021	E1	-	2.60	-	0.102
b2	1.50	1.80	0.060	0.071	G	2.90	3.00	0.114	0.118
С	0.28	0.44	0.011	0.017	Н	2.60	2.85	0.102	0.112
D	4.40	4.60	0.173	0.181	-	-	-	-	-

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